

# Heavy Ion Radiation Effects Microscopy



## Sandia National Laboratories

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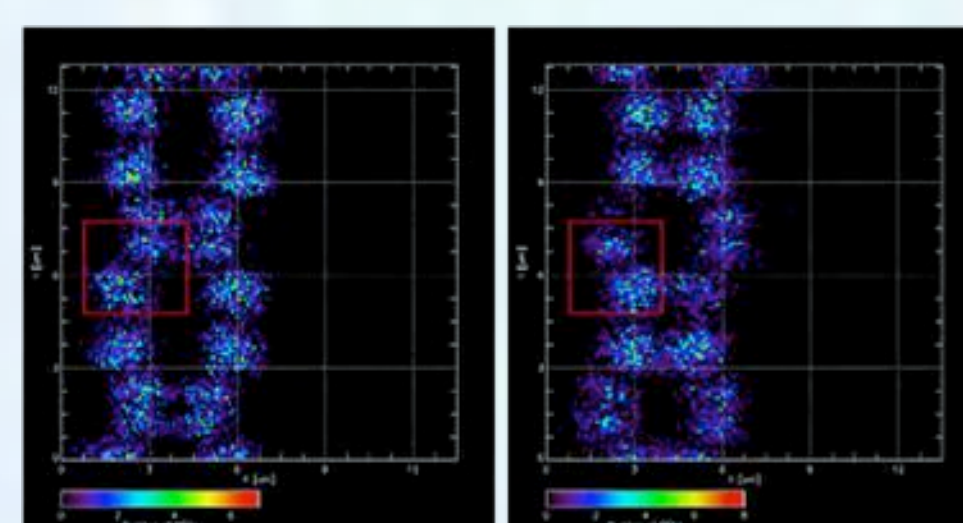
### Problem

#### Background

Advancing IC technology is hindering our ability to microscopically study radiation effects

##### Radiation Effects Microscopy

Typical single event upset (SEU) map showing upset locations in SRAMs depends on the state of the memory cell

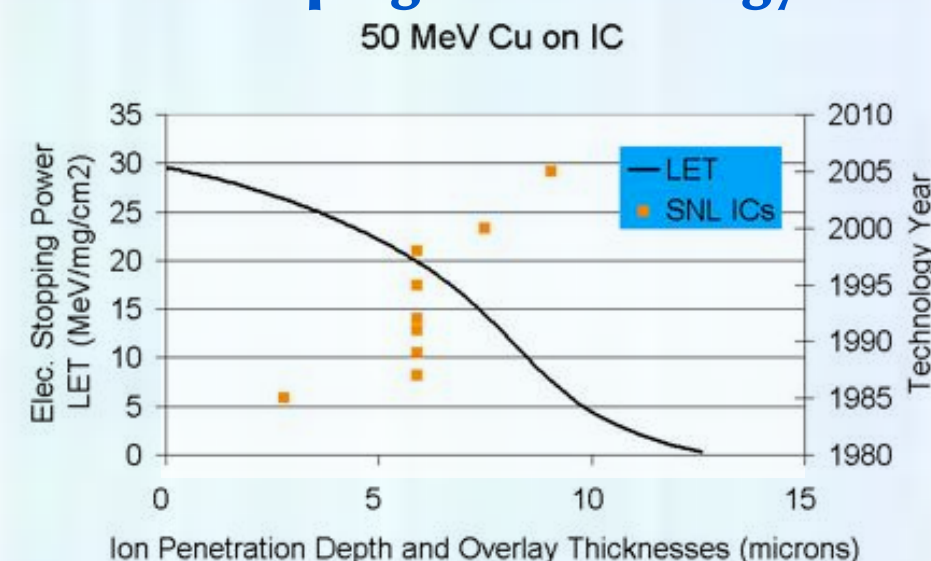


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- Radiation effects microscopy (REM) – used to engineer radhard ICs by pinpointing radiation intolerance to single-event effects
- Traditional REM uses focused, scanned microbeam from ion accelerator

##### Developing IC Technology

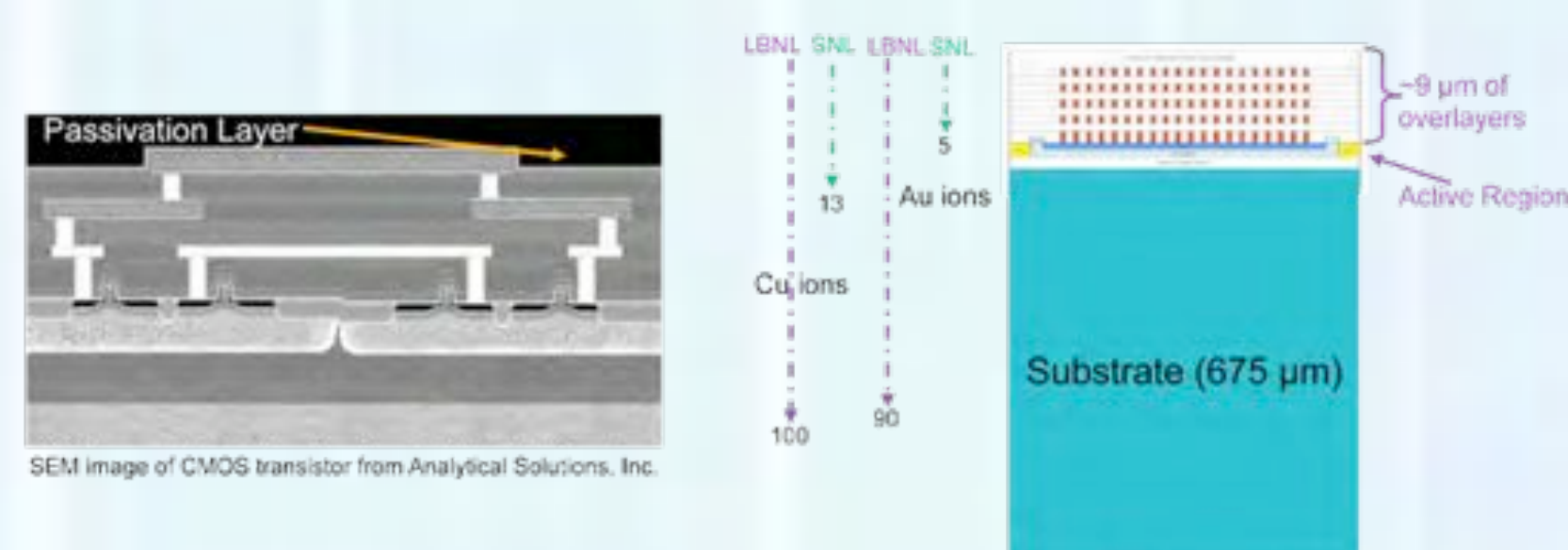


- New technologies continually increase the overlayer thickness on ICs, limiting our ability to probe the active region and study the devices using the tandem.
- Current Sandia technology has 9  $\mu\text{m}$  of overlayers, which is generations behind industry and will continue to increase

#### Project Goal

Require high-energy heavy ions to penetrate overlayers with sufficient linear energy transfer (LET) for REM studies

- Metal, dielectric and passivation layers (as well as flip-chip)  $\rightarrow$  hundreds of microns of material  $\rightarrow$  only high-energy ion beams can penetrate
- Current GeV ions from cyclotron: a potential solution, but extremely hard to focus due to high magnetic rigidity and poor energy resolution



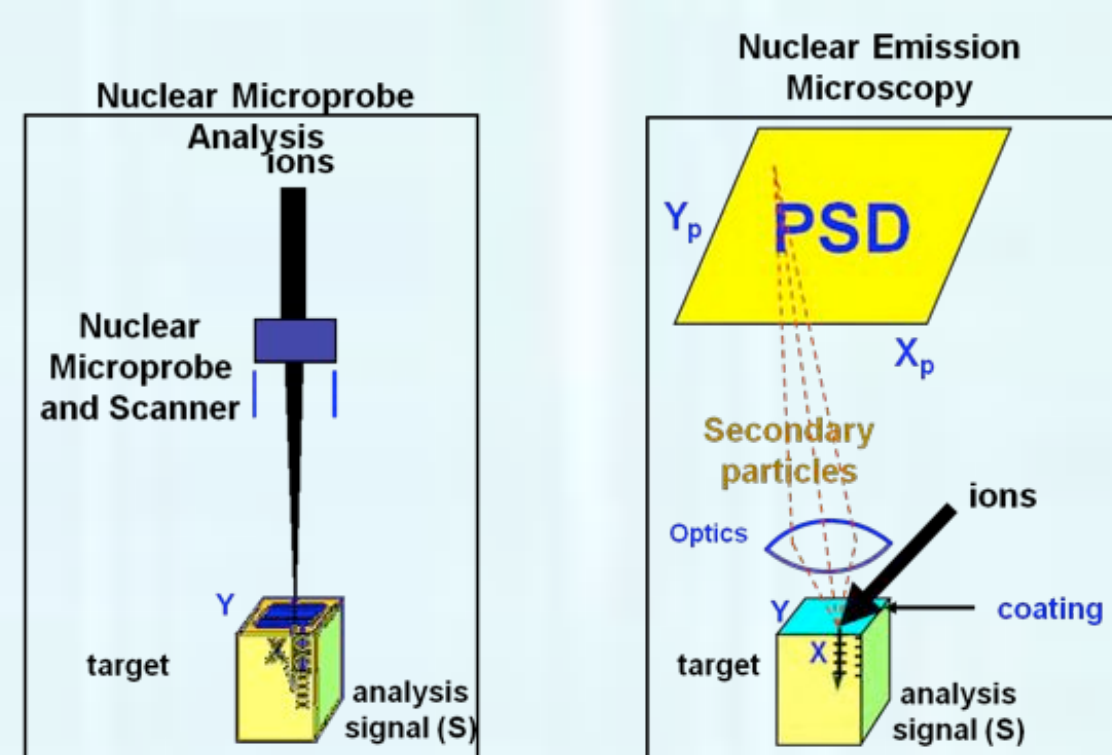
• Goal: To develop a REM technique which allows for the range/LET of a heavy ion cyclotron beam with the spatial resolution of a microbeam

### Approach

#### Hypothesis

Instead of traditional nuclear microprobe analysis (focused, scanned ion beam), use a form of nuclear emission microscopy

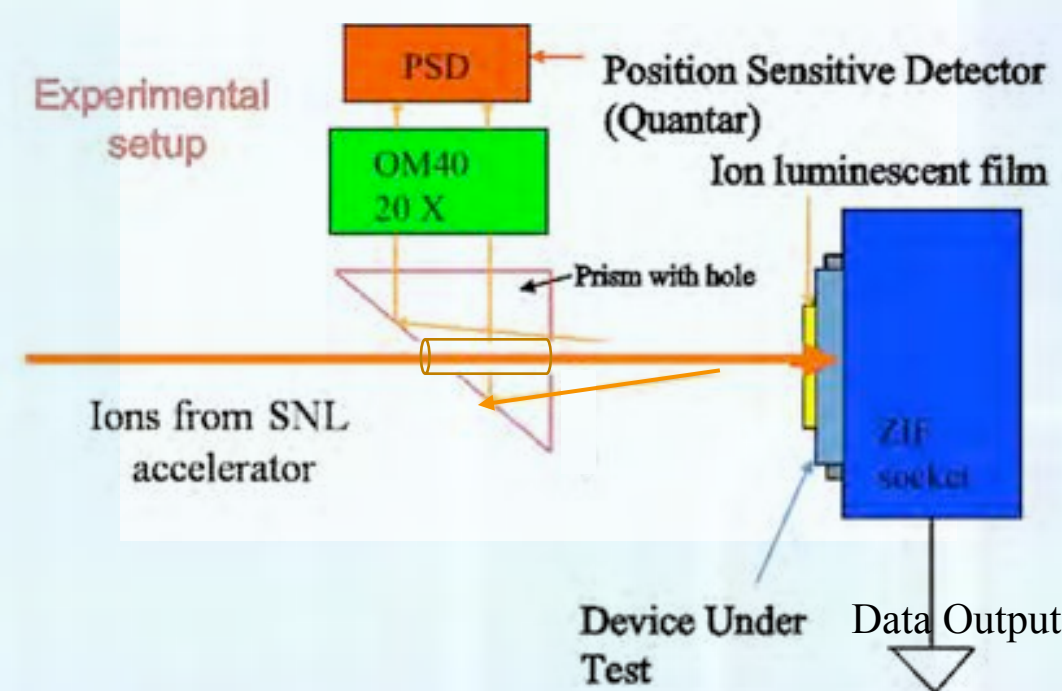
- Use secondary particles (photons) emitted from the location of the ion impact to determine the position of the ion
- Rely on photons and the ion beam induced charge (IBIC) to image radiation sensitivity



#### IPEM Technique

Developed IPEM system on nuclear microprobe line on SNL's tandem accelerator

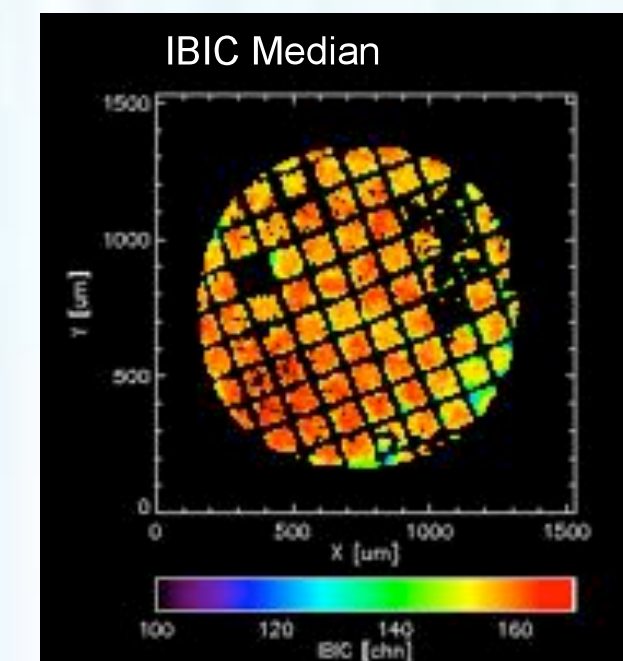
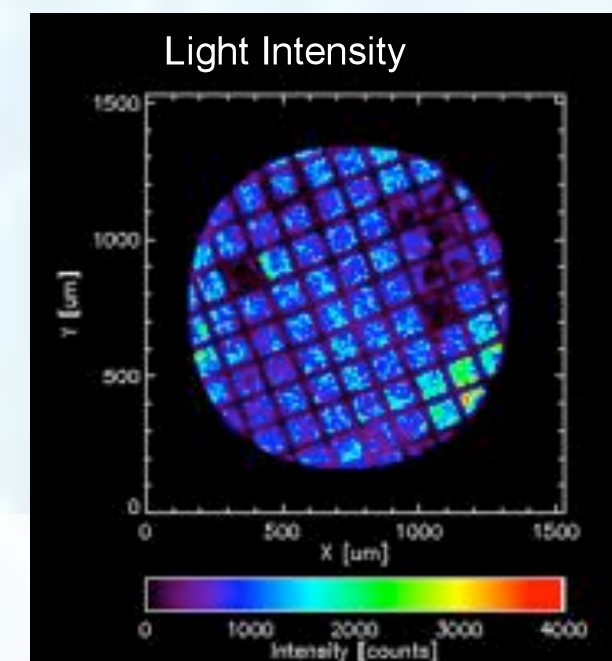
- Ions have two major interactions
  - 1) Ions hit luminescent film and get ion beam-induced luminescence (IBIL)
  - 2) Ions hit chip and create ion beam induced charge (IBIC) and possibly upsets
- Photons produced by film detected with single photon position-sensitive detector (PSD)
- Record photon and IBIC signals in coincidence



### Results

This tabletop version of the IPEM was used for proof-of-concept and to study various luminescent materials

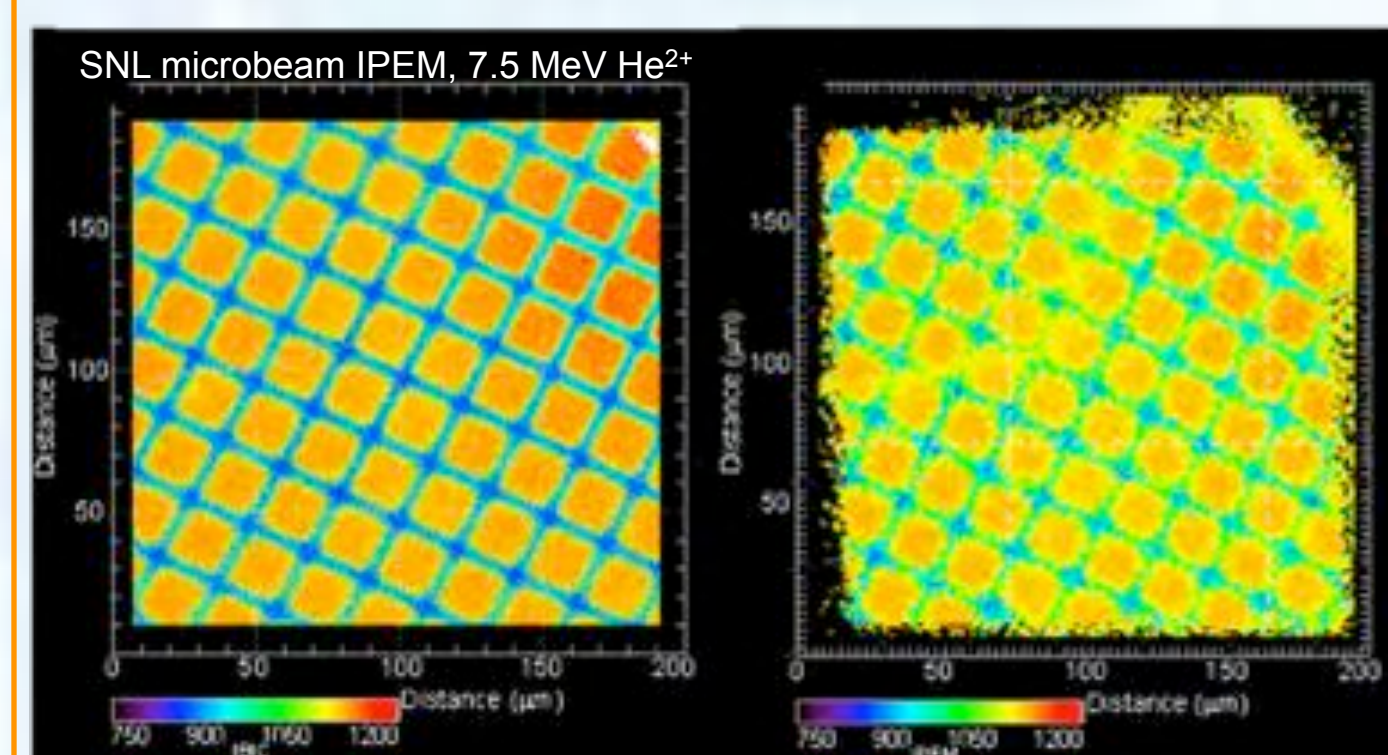
Tabletop IPEM



- **Pros:** Simple design/implementation, easy for basic materials studies
- **Cons:** Limited ion penetration, no single event effects

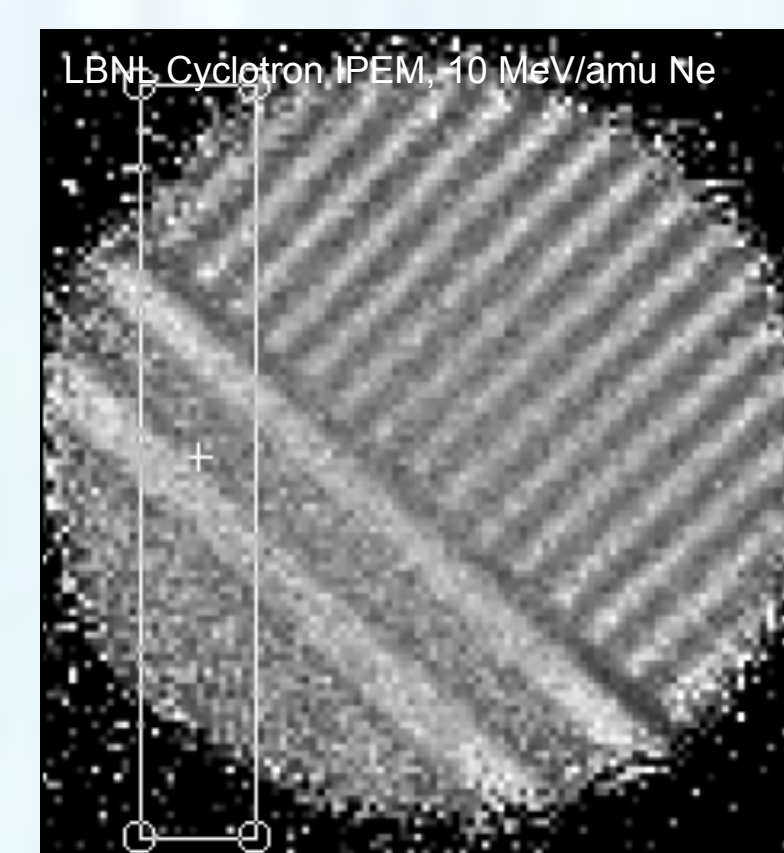
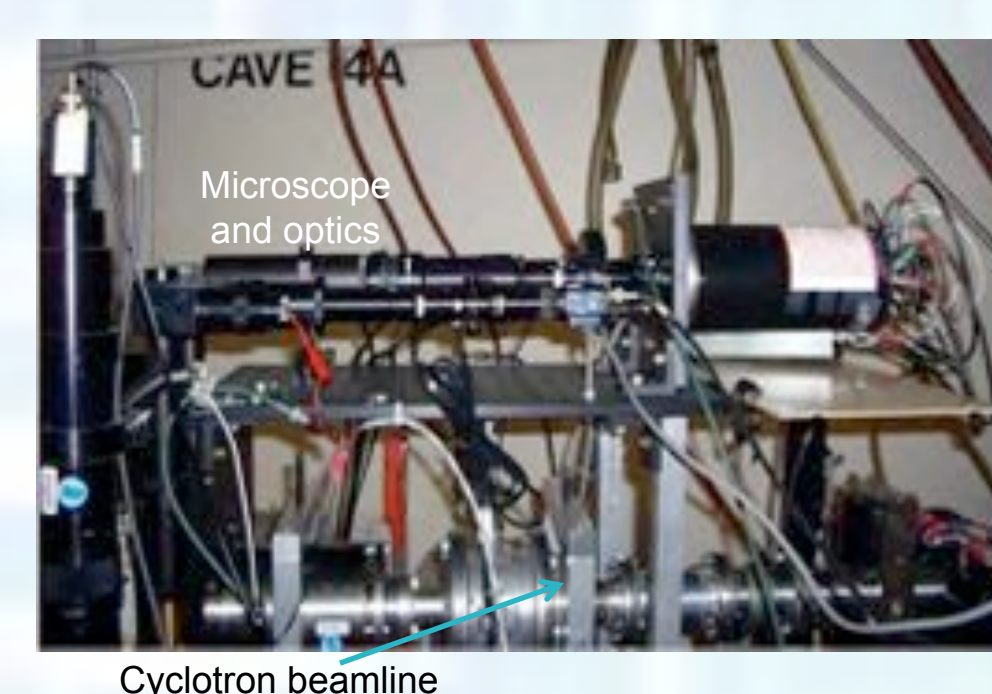
#### Development for Heavy Ions – Accelerator at SNL

- IPEM system installed on SNL's tandem accelerator
- Sample: Diode + 1000 mesh TEM grid + 5  $\mu\text{m}$  GaN film
- IBIC (left) and IPEM-IBIC (right) images
- Signal from diode put in coincidence with photons arriving at detector
- See damage, cracks in GaN



- **Pros:** Various ions/energies, Best spatial resolution achieved ( $\sim 2.5 \mu\text{m}$ )
- **Cons:** In a vacuum chamber, limited ion penetration

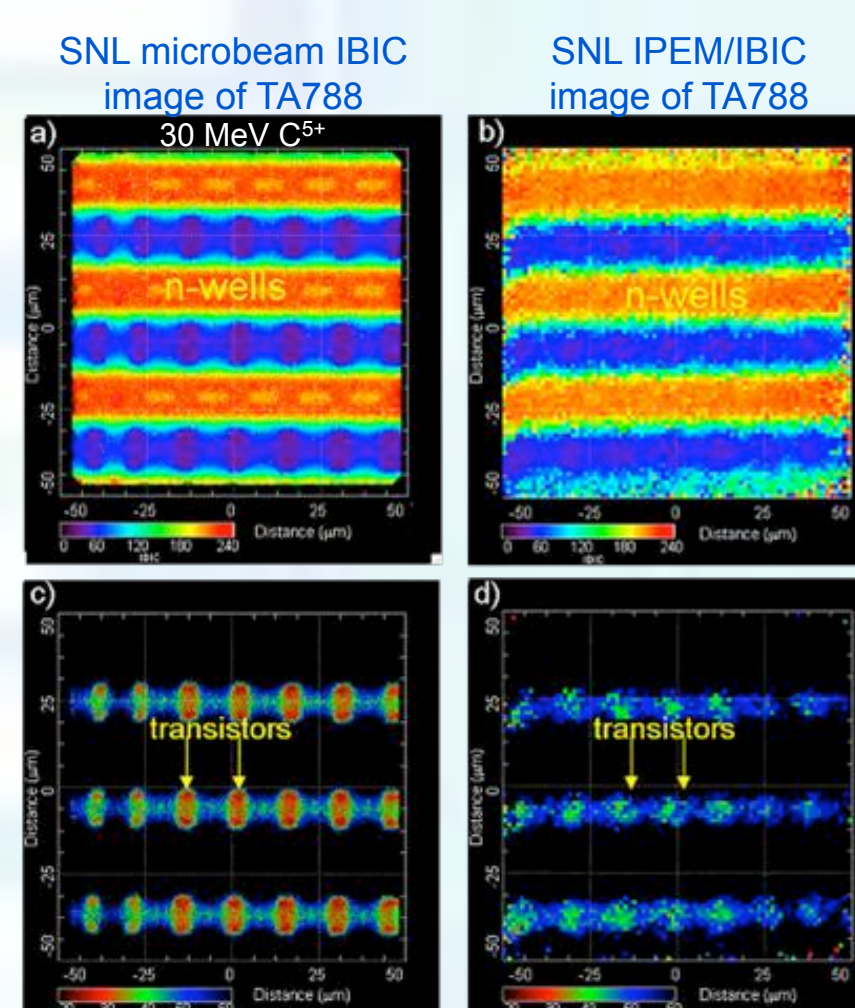
#### Development for High-energy Heavy Ions – 88" Cyclotron at LBNL



- **Pros:** Great ion penetration depth with high LET, Easily change ion species; In-air operation
- **Cons:** Remote automation, Limited facilities/time, Still being developed/optimized

### Significance

#### Focused beam IBIC and IPEM IBIC from SNL



- Future of heavy ion radiation effects microscopy depends on developing scanned microbeams and/or emission microscopes that can be easily used on cyclotrons
- IPEM provides a reasonable solution, and its continuing progress is promising
- The cyclotron IPEM has been installed and is operational
- With IPEM, we can study any structure with high energy heavy ions with  $\sim 5 \mu\text{m}$  resolution to obtain radiation effects information deep into the active region of devices